

# HF

Halogen Free

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	23,12,22	LeiCaiXin
B			优化平面度, 变更掏料结构	24,06,20	Leeson

A

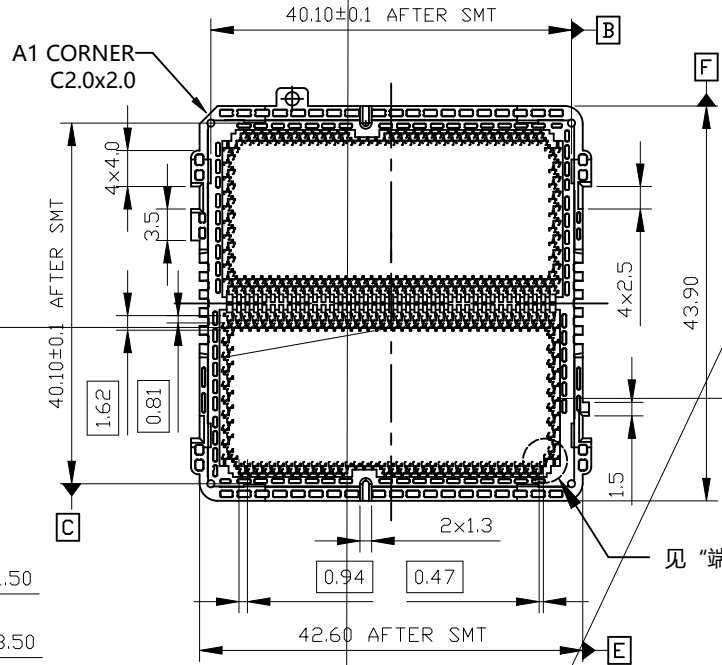
B

C

D

E

F



DEREN LOGO

DATE CODE:

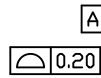
X XX X X

YEAR  
(1~9)

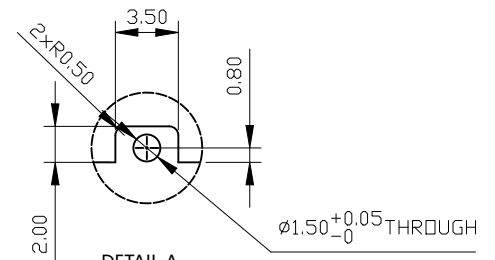
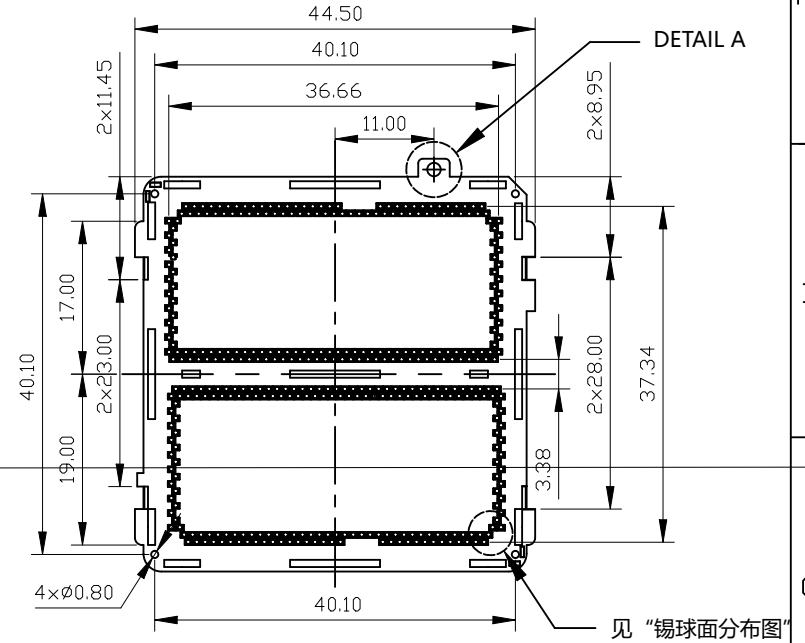
WEEK  
(01~52or53)

DAY  
(1~7)

SHIFT  
(DAY:D, NIGHT:N)



2.30±0.10  
(SEATING PLANE HEIGHT) AFTER SMT



DETAIL A  
SCALE 2:1

TABLE A:

ITEM NO.	TYPE	PART NO.	NAME	SPECIFICATION
3	LGA1718	56ZZC3-004H	CONTACT	Au:30u", Ni:50u"min.
			SOLDER BALL	∅0.50+/-0.02mmSn/Ag/Cu
			RNPCAP	UL94V-0, BLACK
2	LGA1718	56ZZC3-001H	CONTACT	Au:15u", Ni:50u"min.
			SOLDER BALL	∅0.50+/-0.02mmSn/Ag/Cu
			RNPCAP	UL94V-0, BLACK
1	LGA1718	56ZZC3-003H	CONTACT	GOLD FLASH, Ni:50u"min.
			SOLDER BALL	∅0.50+/-0.02mmSn/Ag/Cu
			RNPCAP	UL94V-0, BLACK

DIM	TOL	DIM	TOL
.X	±0.30	.X	±2'
.X	±0.25	.X	±1'
.XX	±0.20		



<b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO., LTD			
C-DWG:	TY	DATE	TITLE: AM5 Socket ASSEMBLY
SC2208066-8	Leeson	24,06,20	P/N: SEE TABLE A
CHECK:	Kenneth	24,06,20	SHEET: 1/5
APPROVAL:	Andy	24,06,20	SCALE: 1:1 UNIT: mm

A

B

C

D

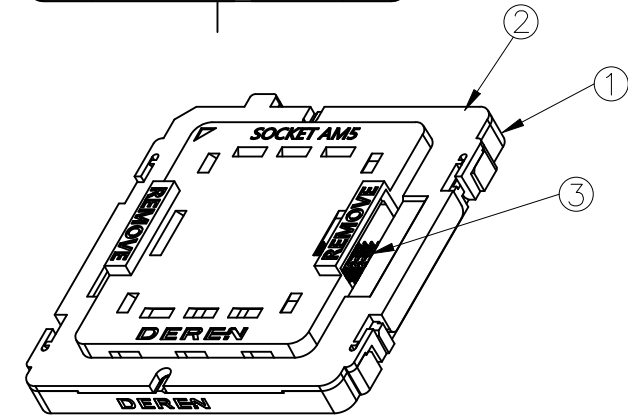
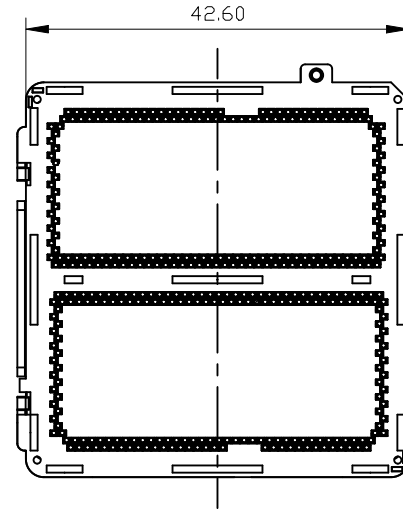
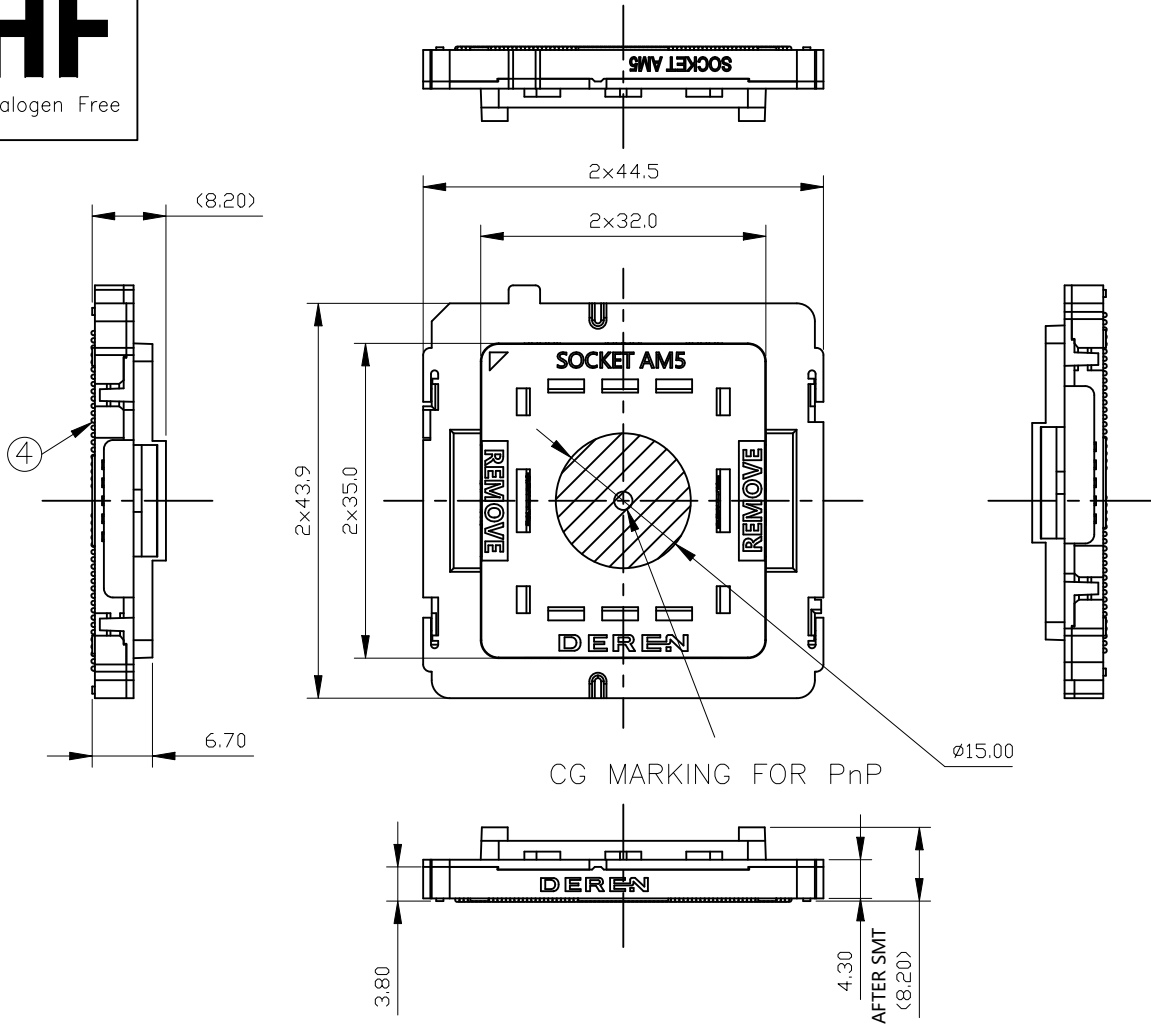
E

F

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### ASSEMBLY COMPONENT LIST

ITEMS	PART NAME	QT'Y
1	HOUSING	1
2	PNPCAP	1
3	CONTACT	1718
4	BALL	1718

DIM	TOL	DIM	TOL	 <b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO., LTD
X.	$\pm 0.30$	X.	$\pm 2'$	
.X	$\pm 0.25$	.X	$\pm 1'$	C-DWG: TY DATE
.XX	$\pm 0.20$			DESIGN: Leeson 24,06,20
				CHECK: Kenneth 24,06,20
				APPROVAL: Andy 24,06,20
				TITLE: AM5 Socket ASSEMBLY
				P/N: SEE TABLE A
				SHEET: 2/5
				SCALE: 1:1 UNIT: mm



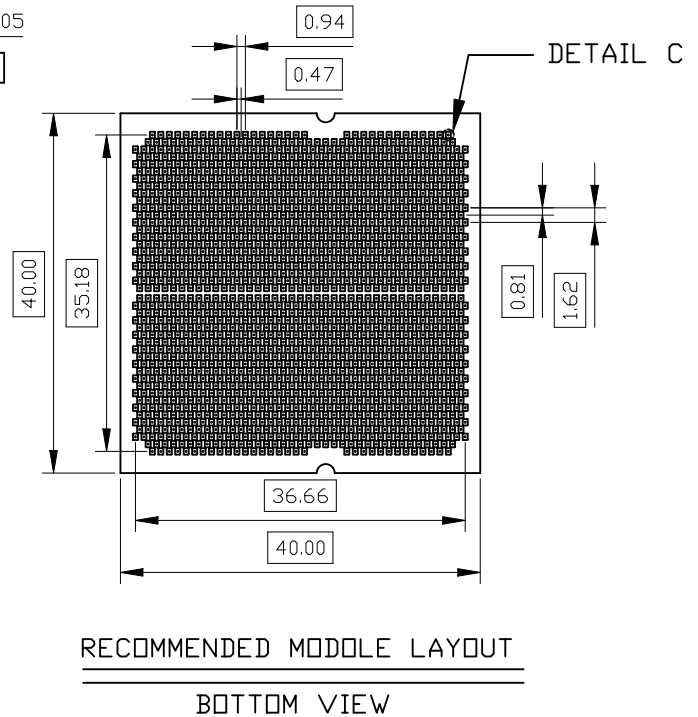
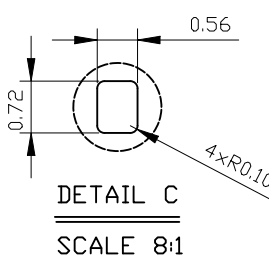
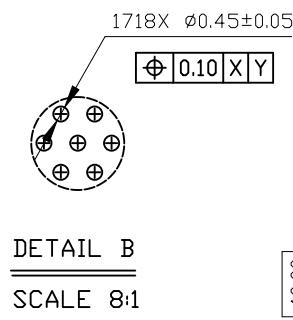
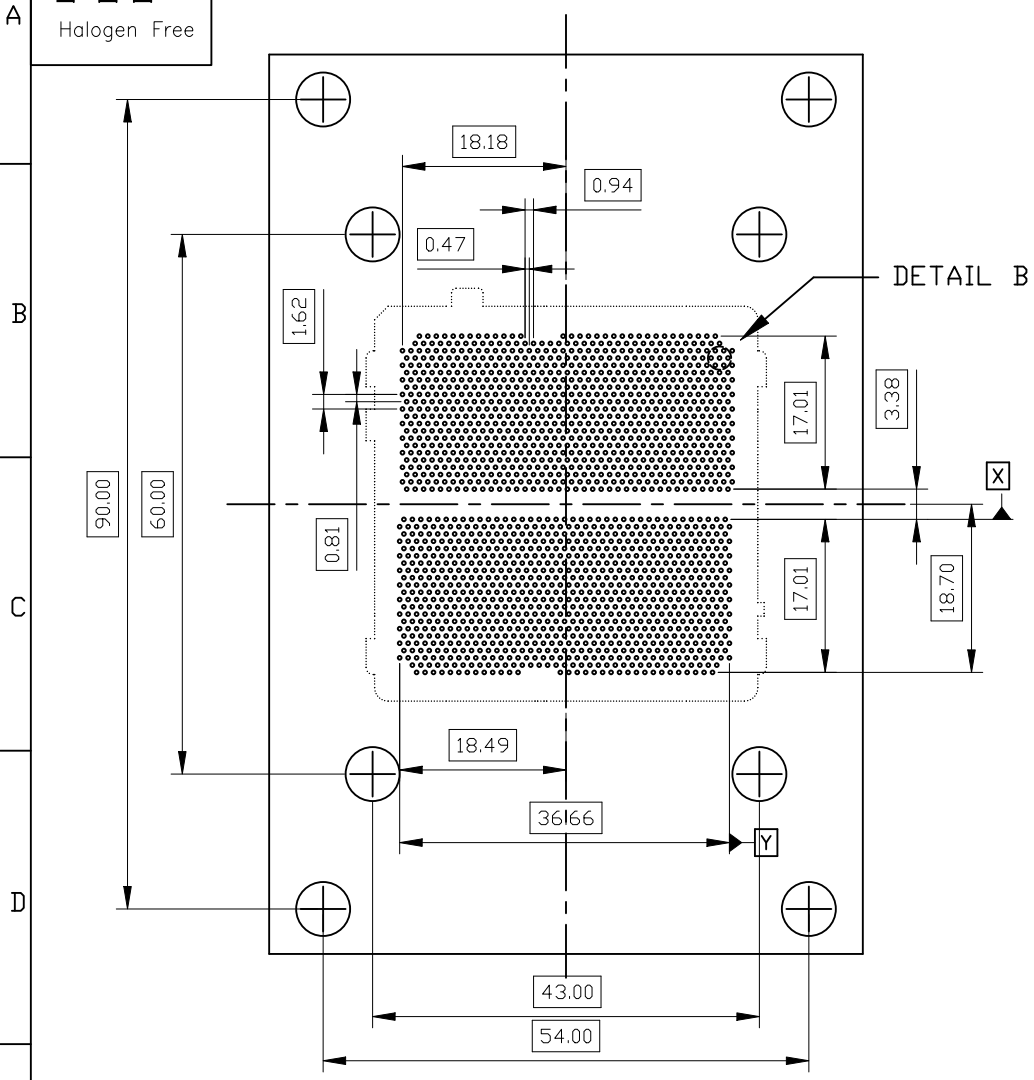
C-DWG: TY DATE  
 DESIGN: Leeson 24,06,20  
 CHECK: Kenneth 24,06,20  
 APPROVAL: Andy 24,06,20  
 TITLE: AM5 Socket ASSEMBLY  
 P/N: SEE TABLE A  
 SHEET: 2/5  
 SCALE: 1:1 UNIT: mm



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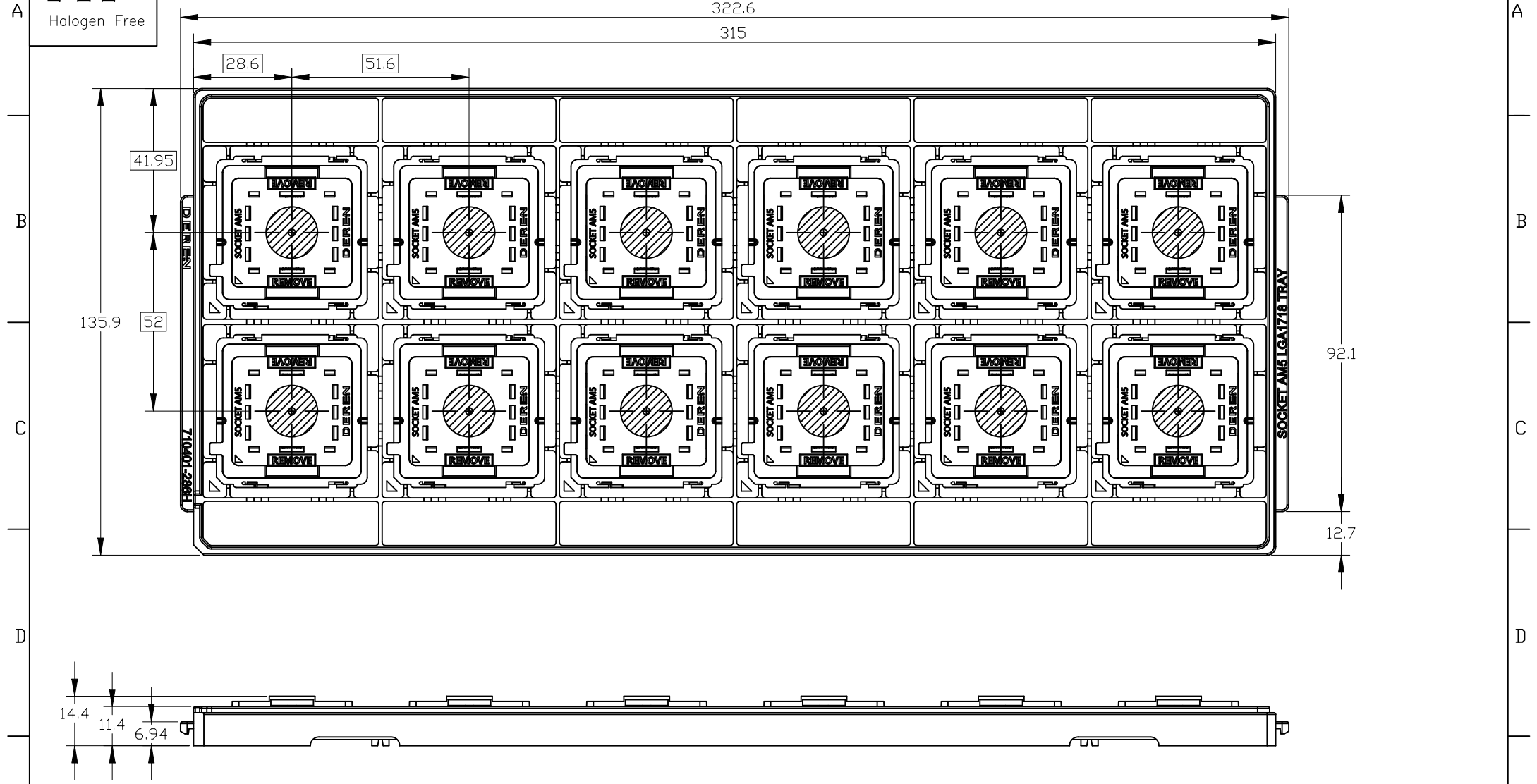




DIM	TOL	DIM	TOL	DEREN SHENZHEN DEREN ELECTRONIC CO., LTD				
X.	$\pm 0.30$	X.	$\pm 2'$	DRAW NO. SC2208066-8	C-DWG:	TY	DATE	TITLE: AM5 Socket ASSEMBLY
.X	$\pm 0.25$	.X	$\pm 1'$		DESIGN:	Leeson	24,06,20	P/N: SEE TABLE A
.XX	$\pm 0.20$			CHECK:	Kenneth	24,06,20	SHEET: 4/5	
				REV.	B	APPROVAL:	Andy	24,06,20
							SCALE: 1:1	UNIT: mm

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DIM	TOL	DIM	TOL	 <b>DEREN</b> SHENZHEN DEREN ELECTRONIC CO., LTD	C-DWG:		TY	DATE	TITLE: AM5 Socket ASSEMBLY			
X.	±0.30	X.	±2'		DRAW NO. SC2208066-8	DESIGN:	Leeson	24.06.20	P/N: SEE TABLE A			
.X	±0.25	.X	±1'	CHECK:		Kenneth	24.06.20	SHEET:	5/5			
.XX	±0.20			REV.	B	APPROVAL:	Andy	24.06.20	SCALE:	1:1	UNIT:	mm